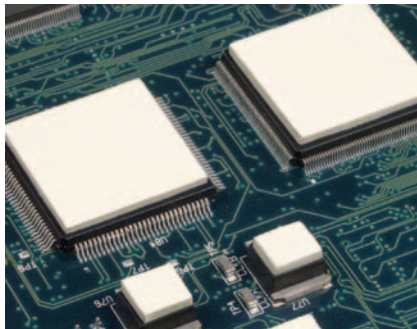


# Gap Pad® 2500S20

Highly Conformable, Thermally Conductive, Reinforced “S-Class” Gap Filling Material

## Features and Benefits

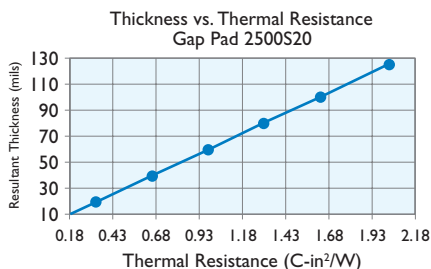
- Thermal conductivity: 2.4 W/m-K
- Low “S-Class” thermal resistance at ultra-low pressures
- Ultra conformable, “gel-like” modulus
- Designed for low-stress applications
- Fiberglass reinforced for puncture, shear and tear resistance



Gap Pad 2500S20 is a thermally conductive, reinforced material rated at a thermal conductivity of 2.4 W/m-K. The material is a filled-polymer material yielding extremely soft, elastic characteristics. The material is reinforced to provide easy handling, converting, added electrical isolation and tear resistance. Gap Pad 2500S20 is well suited for low-pressure applications that typically use fixed standoff or clip mounting. The material maintains a conformable, yet elastic nature that allows for excellent interfacing and wet-out characteristics, even to surfaces with high roughness and/or topography.

Gap Pad 2500S20 is offered with inherent natural tack on both sides of the material allowing for stick-in-place characteristics during application assembly. The material is supplied with protective liners on both sides.

*Note: Resultant thickness is defined as the final gap thickness of the application.*



## TYPICAL PROPERTIES OF GAP PAD 2500S20

PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color	Light Yellow	Light Yellow	Visual
Reinforcement Carrier	Fiberglass	Fiberglass	—
Thickness (inch) / (mm)	0.010 to 0.125	0.254 to 3.175	ASTM D374
Inherent Surface Tack (1- or 2-sided)	2	2	—
Density (g/cc)	3.1	3.1	ASTM D792
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269
Hardness, Bulk Rubber (Shore 00) (1)	20	20	ASTM D2240
Young's Modulus (psi) / (kPa) (2)	5	35	ASTM D575
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	—
<b>ELECTRICAL</b>			
Dielectric Breakdown Voltage (Vac)	>3000	>3000	ASTM D149
Dielectric Constant (1000 Hz)	6.6	6.6	ASTM D150
Volume Resistivity (Ohm-meter)	10 <sup>11</sup>	10 <sup>11</sup>	ASTM D257
Flame Rating	V-O	V-O	U.L. 94
<b>THERMAL</b>			
Thermal Conductivity (W/m-K)	2.4	2.4	ASTM D5470

1) Thirty second delay value Shore 00 hardness scale.  
2) Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch<sup>2</sup>. For more information on Gap Pad modulus, refer to Bergquist Application Note #116.

## Typical Applications

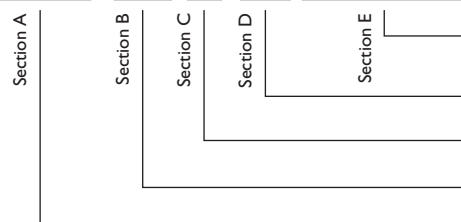
- Between processors and heat sinks
- Between graphics chips and heat sinks
- DVD and CDROM electronics cooling
- Areas where heat needs to be transferred to a frame, chassis or other type of heat spreader

## Configurations Available:

- Sheet form and die-cut parts

## Building a Part Number

GP2500S20 - 0.100 - 02 - 00 - ACME 89302 Rev a



## Standard Options

◀ example

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

0816 = Standard sheet size 8" x 16", or 00 = custom configuration

02 = Natural tack, both sides

Standard thicknesses available: 0.010", 0.015", 0.020", 0.040", 0.060", 0.080", 0.100", 0.125"

GP2500S20 = Gap Pad 2500S20 Material

Note: To build a part number, visit our website at [www.bergquistcompany.com](http://www.bergquistcompany.com).

Gap Pad®: U.S. Patent 5,679,457 and others.